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Investigation on the impact of powder arching in small die filling

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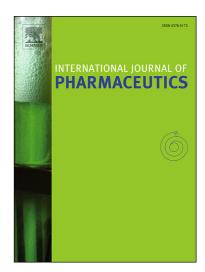
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